

IN THE CLAIMS:

1.-130. (Cancelled)

131. (Original) A method for making a silver-containing film, the method comprising the steps of:

applying a layer of paste to a substrate, said paste including particles dispersed in a carrier liquid, said particles including a metallic phase with greater than about 30 weight percent silver;

removing said carrier liquid from said layer of paste and forming on said substrate a densified layer including silver from said particles;

wherein, said particles being substantially spheroidal, having a weight average size of from about 0.1 micron to about 4 microns, having a size distribution such that at least about 90 weight percent of said particles are smaller than about twice said weight average size and having a mean crystallite size of larger than about 50 nanometers.

132. (Original) The process of Claim 131, wherein:

said particles are comprised substantially of only said metallic phase.

133. (Original) The method of Claim 131, wherein:

said metallic phase comprises a first material phase and said particles further comprise a second material phase being substantially free of silver.

134. (Original) The method of Claim 133, wherein:

said first material phase comprises greater than about 50 weight percent of said particles.

135. (Original) The method of Claim 133, wherein:

said second material phase comprises less than about 30 weight percent of said particles.

136. (Original) The method of Claim 133, wherein:

said first material phase is electrically conductive and said second material phase is dielectric.

137. (Original) The method of Claim 133, wherein:

said substrate comprises a dielectric material for a capacitor and said second material phase of said particles also comprises said dielectric material.

138. (Original) The method of Claim 137, wherein:

said dielectric material is a titanate.

139. (Original) The method of Claim 133, wherein:

said second material phase comprises an oxide material.

140. (Original) The method of Claim 133, wherein:

said second material phase comprises a ceramic material.

141. (Original) The method of Claim 131, wherein:

said step of forming on said substrate a film including silver from said particles comprises heating said particles, on said substrate, to a temperature of greater than about 300°C.

142. (Original) The method of Claim 131, wherein:

said method further comprises preparing a structure of stacked layers including a plurality of first layers including a dielectric material and second layers including said particles; and

heating said structure to a temperature of greater than about 300°C to form a microelectronic structure including a plurality of silver-containing films, having silver from said particles, and including a plurality of dielectric layers, with at least one of said dielectric layers being between two adjacent of said silver-containing films.

143. (Original) The method of Claim 131, wherein:

said particles including silver are first particles and the particulate product further compromises second particles, compositionally different from said first particles, including palladium.